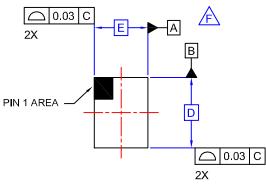
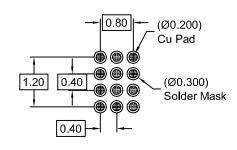


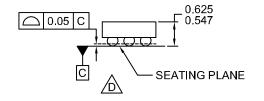
WLCSP12 1.56x1.16x0.586 CASE 567QG ISSUE O

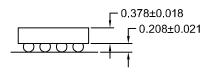
DATE 31 OCT 2016



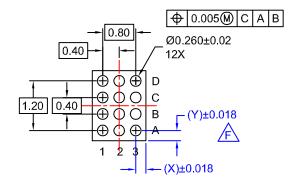


TOP VIEW RECOMMENDED LAND PATTERN (NSMD PAD TYPE)





SIDE VIEWS



BOTTOM VIEW

NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE NOMINAL HEIGHT IS 586 MICRONS ±39 MICRONS (547-625 MICRONS).

FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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|------------------|-------------------------|---|-------------|
| DESCRIPTION: | WLCSP12 1.56x1.16x0.586 | | PAGE 1 OF 1 |

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